DOCUMENT CHANGE REQUEST

DCR number 1621	Changes required for: General	Originator: Steve Thacker	
Date: 2024/10/21	Date sent: 2023/12/15	Organisation: ESCC Executive Secretariat	
Status: IMPLEMENTED			

Title:	Evaluation Test Programme for Integrated Circuits: Monolithic Microcircuits, Wire-bonded, Plastic		
Number:	2269030	Issue:	2

Other documents affected:

9030-3

Page:

Various; See attached spec mark-ups

Paragraph:

Various; See attached spec mark-ups

Original wording:

As per current issue as above

Proposed wording:

In ESCC 9030 (& 2269030):
Amend the contents to facilitate the use of Add-on components (i.e. Capacitors/Resistors) within wire-bonded plastic encapsulated ICs.

A) See attached 9030 Draft 2 spec mark-up for change details (highlighted yellow) in Paras:
3, 4.6, 5.1.1, 5.3.3, 5.3.8, 8.1, 8.4, 9.7, Chart F2, Chart F4A,

B) See attached ESCC 2269030 Draft 2 spec mark-up for change details (highlighted blue) in Paras:
3, 8.3.4.6

Note: Additional changes may be required on behalf of TAS, based on comments and questions raised by TAS, as indicated in the review margin of the attached ESCC9030 Draft 2.
It is requested that these various additional subjects should be discussed with TAS as part of the review process for this DCR.
e.g.
- the possibility to use automotive level Add-on components
- the possibility to add different quality levels to ESCC9030 (which currently only includes a single level)

Justification:

This DCR is raised on behalf of Thales Alenia Space.

TAS wish to expand the scope of ESCC 9030 (& 2269030) to cover their own plastic encapsulated microcircuits by

DOCUMENT CHANGE REQUEST

DCR number 1621
Changes required for: General
Originator: Steve Thacker
Date: 2024/10/21
Date sent: 2023/12/15
Organisation: ESCC Executive Secretariat
Status: IMPLEMENTED

permitting Add-on components to be used with wire-bonded integrated circuit assemblies. i.e. per 9030 issue 1, only Flip-chip devices are permitted to have Add-on components.
Other changes may also be required based on TAS current preferences, that will need to be discussed within ESCC.

Attachments:

escc2269030iss_draft_2x_(ref._dcr_for_tas)_in_review.docx, escc9030iss_draft_2x_(ref._dcr_for_tas)_in_review.docx

Modifications:

DCR1621 Modifications:
For ESCC 9030 issue 2:
See attached Draft 3B with highlighted changes:
- Green highlights: per PSWG conclusion
- Blue highlights: minor additional editorial changes (including changes to the DCR original contents)
- Yellow highlight are the original DCR changes

PSWG change details:
Para. 3 modify the definitions of:
- Wire bonded Integrated Circuit
- Flip-Chip Integrated Circuit

……..

For ESCC 2269000 issue 2:
See attached Draft 3B with highlighted changes:
- Green highlights: per PSWG conclusion
- Blue highlights: minor additional editorial changes (including changes to the DCR original contents)

PSWG change details:
Para. 3 modify the definitions of:
- Wire bonded Integrated Circuit
- Flip-Chip Integrated Circuit

Para. 8.3.3.x: delete the sample sizes from the titles.

Approval signature:

Date signed:

2024-10-21